

FS40SM-5-VB Datasheet N-Channel 250 V (D-S) 175 °C MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	R_{DS(on)} (Ω)	I _D (A)	Q _g (Тур)			
250	0.040 at V _{GS} = 10 V	60	95			
230	0.045 at V _{GS} = 6 V	55	90			

FEATURES

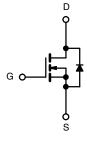
- Trench Power MOSFETS
- 175 °C Junction Temperature
- New Low Thermal Resistance Package
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

Industrial



Top View



N-Channel MOSFET

ABSOLUTE MAXIMUM RATING	S (T _C = 25 °C, unless oth	erwise noted)			
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V _{DS}	250	V		
Gate-Source Voltage	V _{GS}	± 30	V		
Continuous Drain Current ($T_1 = 175 \ ^{\circ}C$)	T _C = 25 °C	1-	60	А	
Continuous Drain Current $(T_j = T/5 C_j)$	T _C = 125 °C	I _D	35		
Pulsed Drain Current	I _{DM}	200	A		
Avalanche Current	I _{AR}	35			
Repetitive Avalanche Energy ^a L = 0.1 mH		E _{AR}	61	mJ	
	T _C = 25 °C	Р	300 ^b		
Maximum Power Dissipation ^a	T _A = 25 °C ^c	– P _D –	3.75	W	
Operating Junction and Storage Temperature R	T _J , T _{stg}	- 55 to 175	°C		

THERMAL RESISTANCE RATINGS							
Parameter	Symbol	Limit	Unit				
Junction-to-Ambient (PCB Mount) ^c	R _{thJA}	40	°C/W				
Junction-to-Case (Drain)	R _{thJC}	0.5					

Notes:

a. Duty cycle \leq 1 %.

b. See SOA curve for voltage derating.

c. When mounted on 1" square PCB (FR-4 material).

SPECIFICATIONS $(T_J = 25)$	°C, unless c	otherwise noted)					
Parameter	Symbol	Test Conditions	Min .	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{DS} = 0 V, I_{D} = 250 \mu A$	250			V	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$	2		4	v	
Gate-Body Leakage	I _{GSS}	V_{DS} = 0 V, V_{GS} = ± 30 V			± 250	nA	
		$V_{DS} = 250 \text{ V}, V_{GS} = 0 \text{ V}$	1		1		
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 250 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 ^{\circ}\text{C}$			50	μA	
		$V_{DS} = 250 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 175 ^{\circ}\text{C}$			250		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$	70			А	
		V _{GS} = 10 V, I _D = 30 A		0.040			
	Б	V_{GS} = 10 V, I _D = 30 A, T _J = 125 °C		0.091		-	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V_{GS} = 10 V, I _D = 30 A, T _J = 175 °C		0.123		Ω	
		$V_{GS} = 6 V, I_D = 25 A$		0.045			
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 30 A		70		S	
Dynamic ^b	•	•	•	•			
Input Capacitance	C _{iss}			5000			
Output Capacitance	C _{oss}	V_{GS} = 0 V, V_{DS} = 25 V, f = 1 MHz		300		pF	
Reverse Transfer Capacitance	C _{rss}			170			
Total Gate Charge ^c	Qg			95	140	nC	
Gate-Source Charge ^c	Q _{gs}	V_{DS} = 125 V, V_{GS} = 10 V, I_{D} = 45 A		28			
Gate-Drain Charge ^c	Q _{gd}			34			
Gate Resistance	R _g	f = 1 MHz		1.6		Ω	
Turn-On Delay Time ^c	t _{d(on)}			22	35		
Rise Time ^c	t _r	V_{DD} = 100 V, R_L = 2.78 Ω		220	330	20	
Turn-Off Delay Time ^c	t _{d(off)}	${ m I}_{ m D}\cong$ 45 A, ${ m V}_{ m GEN}$ = 10 V, ${ m R}_{ m g}$ = 2.5 Ω		40	60	ns	
Fall Time ^c	t _f			145	220	1	
Source-Drain Diode Ratings and Cha	aracteristics ($T_{\rm C} = 25 \ {}^{\circ}{\rm C})^{\rm b}$		•			
Continuous Current	ا _S				45	^	
Pulsed Current	I _{SM}				70	A	
Forward Voltage ^a	V _{SD}	I _F = 45 A, V _{GS} = 0 V		1	1.5	V	
Reverse Recovery Time	t _{rr}			150	225	ns	
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = 45 A, di/dt = 100 A/μs		12	18	А	
Reverse Recovery Charge	Q _{rr}			0.9	2	μC	

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

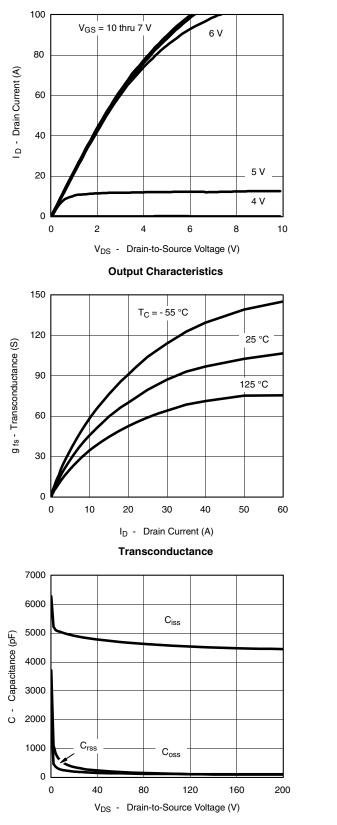
b. Guaranteed by design, not subject to production testing.

c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

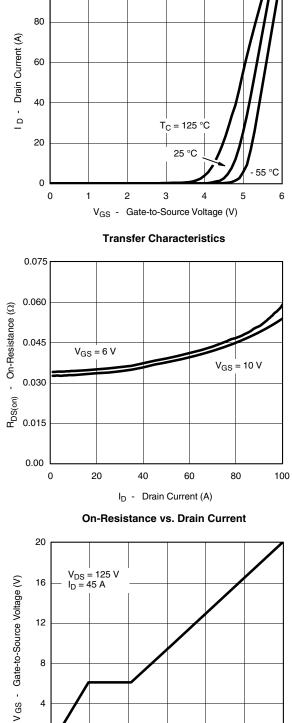
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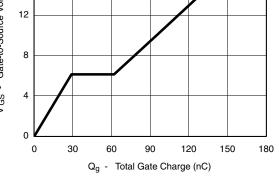


TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





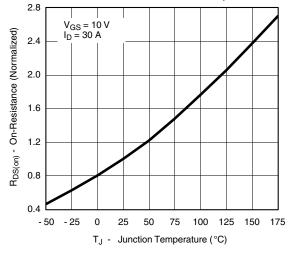
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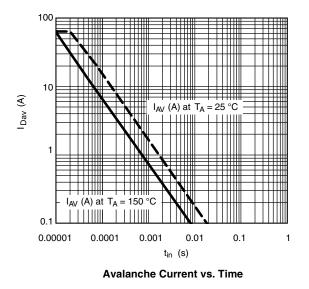
Gate Charge

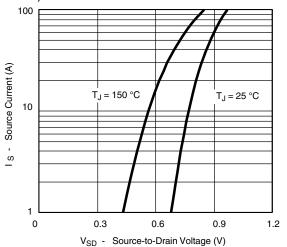


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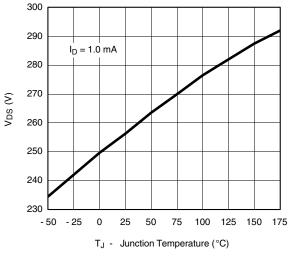


On-Resistance vs. Junction Temperature





Source-Drain Diode Forward Voltage

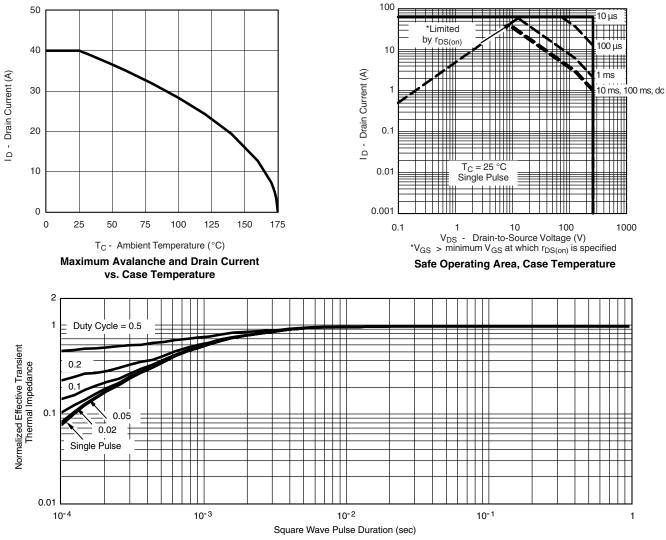


Drain Source Breakdown vs. Junction Temperature

FS40SM-5-VB

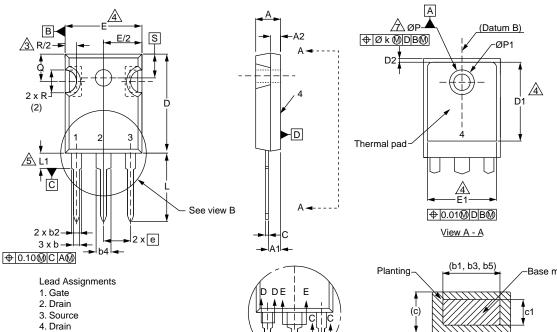


THERMAL RATINGS



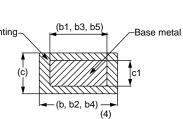
Normalized Thermal Transient Impedance, Junction-to-Case





TO-247AC (High Voltage)

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Section C - C, D - D, E - E

View B

	MILLIMETERS		INCHES			MILLIMETERS		INCHES			
DIM.	MIN.	MAX.	MIN.	MAX.	DIM.	MIN.	MAX.	MIN.	MAX.		
А	4.58	5.31	0.180	0.209	D2	0.51	1.30	0.020	0.051		
A1	2.21	2.59	0.087	0.102	E	15.29	15.87	0.602	0.625		
A2	1.17	2.49	0.046	0.098	E1	13.72	-	0.540	-		
b	0.99	1.40	0.039	0.055	е	5.46 BSC		0.215 BSC			
b1	0.99	1.35	0.039	0.053	Øk	0.254		0.254 0.0		010	
b2	1.53	2.39	0.060	0.094	L	14.20	16.25	0.559	0.640		
b3	1.65	2.37	0.065	0.093	L1	3.71	4.29	0.146	0.169		
b4	2.42	3.43	0.095	0.095 0.135 N 7.62 BSC		7.62 BSC		N 7.62 BSC		0.300	BSC
b5	2.59	3.38	0.102	0.133	ØP	3.51	3.66	0.138	0.144		
С	0.38	0.86	0.015	0.034	Ø P1	-	7.39	-	0.291		
c1	0.38	0.76	0.015	0.030	Q	5.31	5.69	0.209	0.224		
D	19.71	20.82	0.776	0.820	R	4.52	5.49	0.178	0.216		
D1	13.08	-	0.515	-	S 5.5		5.51 BSC		7 BSC		



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